

# **MBR20150CT Dual High Voltage Schotty Rectifier**

## Features:

- Low Forward Voltage Drop
- Low Power Loss and High Efficiency
- High Surge Capability
- Rohs Compliant
- Matte Tin(Sn) Lead Finish
- Terminal Leads Surface is Corrosion Resistant and can withstand to 260°C
- Wave Soldering or per MIL-STD-750 Method 2026.



Mark : MBF

TO-220	PIN3	0-
R20150CT		

# MBR20150CT — Dual High Voltage Schotty Rectifier 0 PIN2

August 2008

## Absolute Maximum Ratings\* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	150	V	
V <sub>R</sub>	Maximum DC Reverse Voltage	150	V	
I <sub>F(AV)</sub>	Average Rectified Forward Current, Tc=120°C	10 (Per Leg) 20(Per Device)	А	
I <sub>FSM</sub>	Peak Forward Surge Current, 8.3mS Half Sine wave	150	А	
T <sub>STG</sub> Storage Temperature Range		-55 ~ 150	°C	
TJ	Operating Junction Temperature	150	°C	

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### Thermal Characteristics\* Ta=25°C unless otherwise noted

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case per Leg	1.5	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient per Leg	62.5	°C/W

\* MIL standard 883-1012 & JESD51-10

## Electrical Characteristics\* T<sub>a</sub>=25°C unless otherwise noted

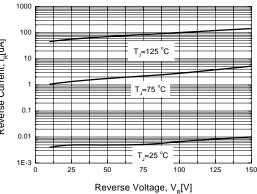
Symbol Parameter		Test Condition		Min.	Max.	Unit
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 150V V <sub>R</sub> = 150V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C		0.2 5	mA
V <sub>F</sub>	Forward Voltage	$I_{F}$ = 10A $I_{F}$ = 10A $I_{F}$ = 20A $I_{F}$ = 20A	$T_{C} = 25 \text{ °C}$ $T_{C} = 125 \text{ °C}$ $T_{C} = 25 \text{ °C}$ $T_{C} = 125 \text{ °C}$		0.85 0.75 0.95 0.85	V

\* DC Item are tested by Pulse Test : Pulse Width≤300us, Duty Cycle≤2%

© 2008 Fairchild Semiconductor Corporation MBR20150CT Rev. 1.0.0

#### **Typical Performance Characteristics** Figure 1. Forward Current Characteristics 1000 100 10 Forward Current, I<sub>F</sub>[A] Reverse Current, I<sub>R</sub>[uA] 10 125 1 75 °C 0.1 0.1 25 0.01 0.01 L 0.0 1E-3 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0 25 50 Forward Voltage Drop, $V_{F}[V]$ **Figure 3.Junction Capacitance** Figure 4. Power Derating 30 1 0.9 0.8 0.7 0.6 Average Forward Current, I $_{F(AV)}[A]$ =1mhz 25 Juntion Capacitance, C<sub>[</sub>[nF] DC 0.5 20 0.4 15 0.3 10 0.2 5 0 L 0 0.1 L 0 25 50 75 2 4 6 8 10 Case Temperature, $T_c[^{\circ}C]$ Reverse Voltage, V<sub>R</sub>[V]

#### Figure 2. Reverse Leakage Current



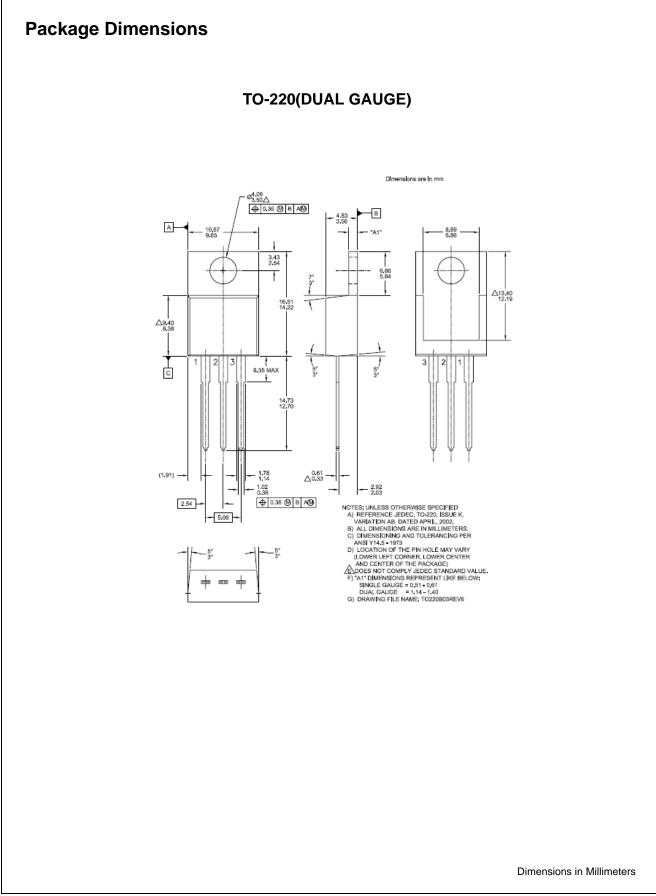
© 2008 Fairchild Semiconductor Corporation MBR20150CT Rev. 1.0.0

www.fairchildsemi.com

150

100

125





SEMICONDUCTOR

#### TRADEMARKS

The following are registered and unregistered trademarks and service marks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx®	Green FPS™	Power247 <sup>®</sup>	SuperSOT™-8
Build it Now™	Green FPS™ e-Series™	POWEREDGE <sup>®</sup>	SyncFET™
CorePLUS™	GTO™	Power-SPM™	The Power Franchise <sup>®</sup>
CROSSVOLT™	<i>i-Lo</i> ™	PowerTrench <sup>®</sup>	piewer franchise
CTL™	IntelliMAX™	Programmable Active Droop™	franchise
Current Transfer Logic™	ISOPLANAR™	QFET®	TinyBoost™
EcoSPARK <sup>®</sup>	MegaBuck™	QS™	TinyBuck™
F	MICROCOUPLER™	QT Optoelectronics <sup>™</sup>	TinyLogic <sup>®</sup>
Fairchild <sup>®</sup>	MicroFET™	Quiet Series™	TINYOPTO™
Fairchild Semiconductor <sup>®</sup>	MicroPak™	RapidConfigure™	TinyPower™
FACT Quiet Series™	MillerDrive™	SMART START™	TinyPWM™
FACT <sup>®</sup>	Motion-SPM <sup>™</sup>	SPM®	TinyWire™
FAST <sup>®</sup>	OPTOLOGIC®	STEALTH™	µSerDes™
FastvCore™	OPTOPLANAR <sup>®</sup>	SuperFET™	UHC®
FPS™	®	SuperSOT™-3	UniFET™
FRFET <sup>®</sup>	PDP-SPM™	SuperSOT™-6	VCX™
Global Power Resource <sup>sm</sup>	Power220 <sup>®</sup>		

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

#### As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be pub- lished at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontin- ued by Fairchild semiconductor. The datasheet is printed for reference infor- mation only.

## PRODUCT STATUS DEFINITIONS